

Metalized Fiber (P Series)

Rev 11

Description

A metal film is deposited on the fiber surface by sputtering process. Metalized fiber can be soldered into a package to achieve hermetical sealing and provide high environmentally reliable interconnection for optical devices. The metalized fiber is widely used in passive and active devices.

Key Features

- Hermetical Sealing
- High Environmentally Reliable Interconnection

Applications

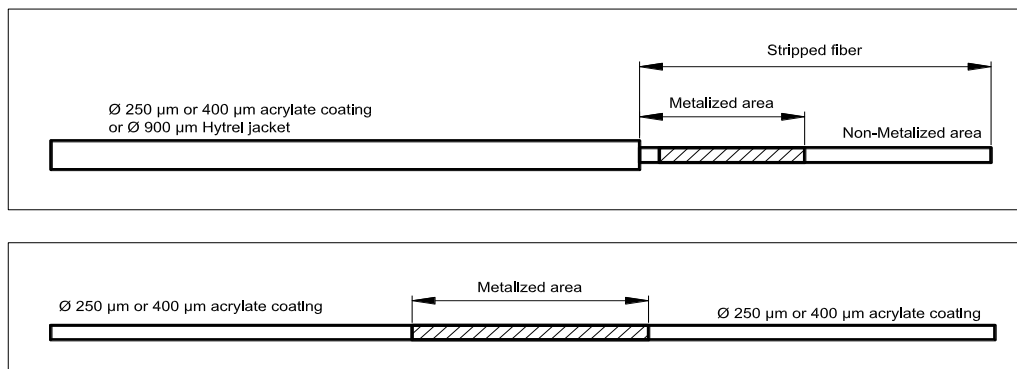
- Hermetic Feed-Throughs
- Integrated Optics Packaging
- Diode Pigtailling

Specifications

Parameter	Unit	Value
Film Composition	-	Ti/Ni/Au (other materials available on request)
Coating Thickness	nm	100-1000 (other thickness available on request)
Plating Length Tolerance	mm	± 1
Polarization Extinction Ratio (PM Fiber Type)	dB	≥ 20
Recommended Minimum Bend Diameter	mm	25
Helium Leak Rate	Pa.m ³ /s	$\leq 1.0 \times 10^{-9}$
Pull Strength	N	≥ 5
Fiber Length Tolerance	%	± 10 or specify
Recommended Soldering Temperature	°C	< 300
Recommended Soldering Time	S	< 3
Storage Temperature	°C	- 40 to + 85

¹Single or dual zone metallization available, mid-span metallization available.

Package Dimensions



Ordering Information

P-①-②-③-④-⑤

①: Fiber Type	②: Key Width (for FC Type)	③: Connector Type	④: Fiber Jacket
F - SMF-28 Fiber	R - 2.02 mm	1 - FC/UPC 5 - LC/UPC	B - 250 µm Bare Fiber
H - HI 1060 Fiber		2 - FC/APC 6 - LC/APC	T - 900 µm Tight Buffer
P - PM 1550 Panda Fiber	⑤: Fiber Length	3 - SC/UPC N - None	S - Specify
S - Specify	1 - 1.0 m	4 - SC/APC S - Specify	
	S - Specify		